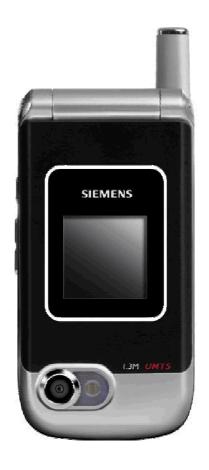


Service Repair Documentation Level 3 (basic) S80/82/SFG75



Release	Date	Department	Notes to change
R 1.0	22.12.2005	BenQ CC S CES	New document

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1 Introduction

This document describes the performance description for Siemens service partners.

1.1 Purpose

This Service Repair Documentation is intended to carry out repairs on BenQ Mobile repair level 3 basic. The described failures shall be repaired in Siemens authorized local workshops only,

The level 3(former Level 2.5e) partners are obliged to repair level 2 classified boards, up to their repair level, under consideration of the information given by level 3 repair instruction.

All repairs have to be carried out in an ESD protected environment and with ESD protected equipment/tools. For all activities the international ESD regulations have to be considered.

Assembling/disassembling has to be done according to the latest S80 Level 2 repair documentation. It has to be ensured that every repaired mobile Phone is checked according to the latest released General Test Instruction document (both documents are available in the Technical Support section of the C-market).

Check at least weekly C-market for updates and consider all S80 related Customer Care Information

S80 Part number on IMEI label:

Scrap Handling: All Scrap information given in this manual are related to the SCRAP-Rules and instructions.

Attention: Consider the new "LEAD-FREE" soldering rules (available in the communication market), avoid excessive heat.

1.2 Scope

This document is the reference document for all BenQ mobile authorised Service Partners which are released to repair BenQ mobile phones up to level 2.5 light.

1.3 Terms and Abbreviations

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2 List of available level 3 basic parts

(According to Component Matrix V1.11 - check C-market for updates)

ID	Order Number	Description CM
1200	1 50334 707 C522	CONNECT SKT60P AXK7L60227
J200	L00004-291-C022	BQ20.L1096.060
U800	L50851-Z1901-A62	ANT 3*5.1*5 56E12 BQ20.M0007.021
1302	I 50334-707-C523	CONNECTOR DC PWR 2P
0002	200004-201-0020	BQ20.N2002.021
J301	I 50334-797-C524	CON BATT3P CBE-4517-2904H
		BQ21.N0036.011
U852	L50334-Z97-C525	CONN SPRING SBS23-2K30F00
		BQ21.N0045.011
J250	L50334-Z97-C526	CONN I/O 10P ACT/916-2941
		BQ2K.N0083.001 CONN SIM 6P D2.54 302-368
J351	L50334-Z97-C527	BQ21.N0050.001
		CONN MINI SD 9P 500525
J350	L50334-Z97-C528	BQ21.N0058.011
J201	L50334-Z97-C529	CONN BTB D1.5 18P BQ21.N1003.011
J202	L50315-Z77-C261	SWI VOLUME KEY 5P BQ21.P0004.005
1200	1 50450 4405 440 4	ASS LOUD SPEAK. CONN.
J300	L50158-A185-A16-1	S80_BQ60.H0916.001
1251	I 50150 A105 A17 1	ASSY CONN. MIC WHITE
	L30130-A103-A17-1	S80_BQ65.G0101.004
	I 50840-I 2133-D670	DISDIODE LED BL-HB536G
		BQ83.00536.071
	L50810-U6228-D670	IC PER HALL A3212ELH BQ74.03212.09Y
		FUSE 1A 24V F0603 1608FF
	L50145-A820-Y23	BQ69.41004.001
		SWITCH ANT MS-147 HIROSE
U801	L50145-K280-Y415	BQ69.50017.001
	. =00=4 =465 : : : : : : : : : : : : : : : : : : :	ANT 2.4GHz AT5020-B2R8HAA
	L50851-Z1901-A63	BQ69.F0005.021
	J200 U800 J302 J301 U852 J250 J351 J350 J201	J200 L50334-Z97-C522 U800 L50851-Z1901-A62 J302 L50334-Z97-C523 J301 L50334-Z97-C524 U852 L50334-Z97-C525 J250 L50334-Z97-C526 J351 L50334-Z97-C527 J350 L50334-Z97-C528 J201 L50334-Z97-C528 J201 L50334-Z97-C529 J202 L50315-Z77-C261 J300 L50158-A185-A16-1 MMI board L50840-L2133-D670 MMI board L50810-U6228-D670 F250 F300 L50145-A820-Y23

3 Hardware requirements

(According to General soldering information V1.3 - check C-market for updates)

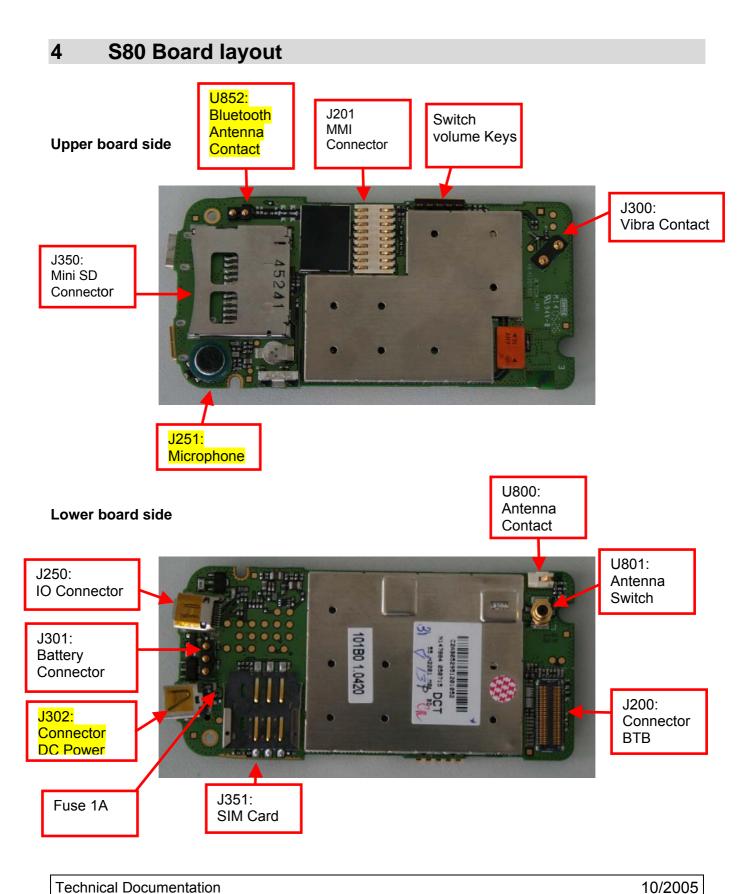
Jigs, Tools and working materials for all described repairs:

- hot air blower
- soldering gun
- tweezers
- flux
- solder

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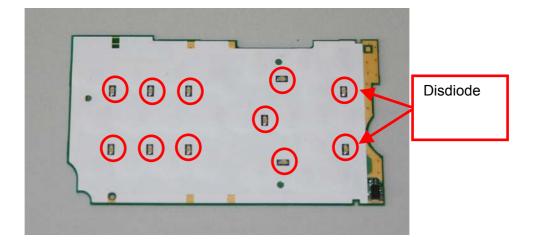


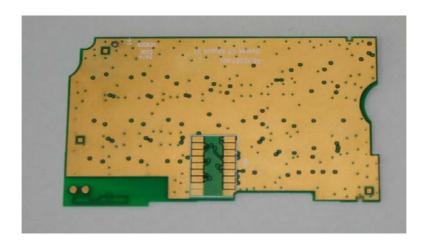
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MMI Board

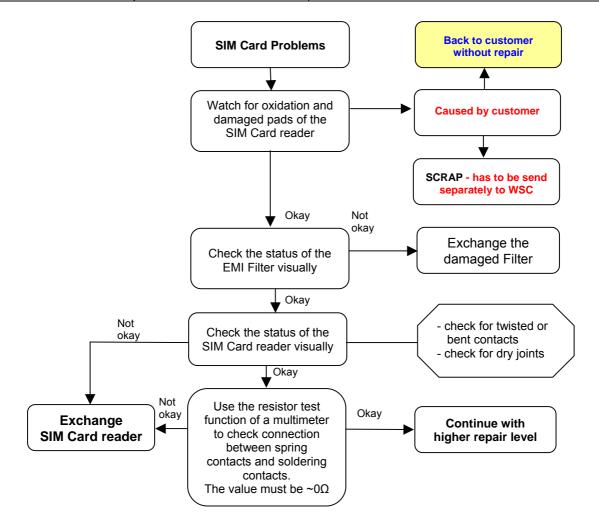






5 SIM Card Problems

Fault Symptoms	
Customer:	GRT:
Handset does not accept SIM card	SIM Card Problems



Connector SIM Card Reader

Use soldering iron to remove defective component. Avoid excessive heat! Watch surrounding components! Resolder new component afterwards.

E-commerce order number: L50634-Z97-C406

E-commerce order name: CONNECTOR SIM CARD READER R65 (B)

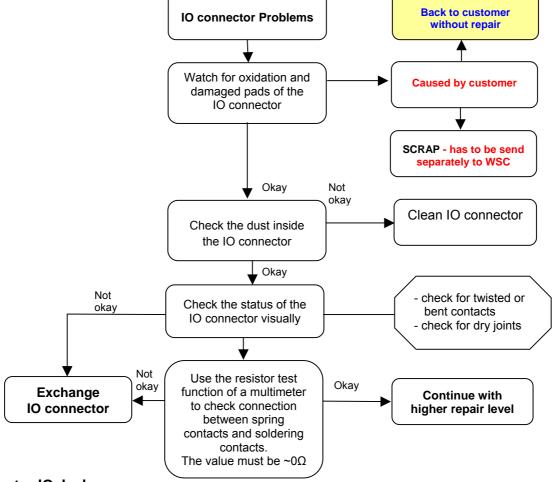
Soldering temperature: ~ 360°C TIP Temp.

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6 IO Connector Problems

Customer: Charging Problems Problems with external loudspeaker or microphone when using a car kit Problems with accessories connected at the IO connector



Connector IO Jack

Use soldering iron to remove defective component. Avoid excessive heat! Watch surrounding components! Resolder new component afterwards.

E-commerce order number: L50334-Z97-C526

E-commerce order name: CONN I/O 10P ACT/916-2941 BQ2K.N0083.001

Soldering temperature: ~ 360°C TIP Temp.

IRIS Diagnose Code: 46100 Interface/Charging Connector/Mechanical Damage

47300 Interface/Data Interface/Mechanical Damage 4B100 Interface/Headset Connector/Mechanical Damage

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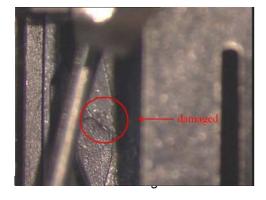
Important additional soldering hints

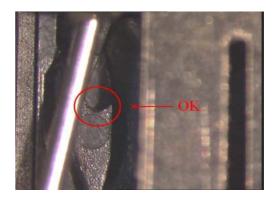
The MMC Reader is located on the opposite of the SLIM-Lumberg connector. Therefore the risk to damage the plastic material of this MMC-Reader is potentially high if excessive heat is used while removal or soldering of the SLIM-Lumberg connector.

Please follow these instructions:

- a) Remove the SLIM-Lumberg connector with a soldering iron and Resolder Wick
- b) Clean the Pads afterwards
- c) Solder the new connecter by using soldering iron under consideration of the max. allowed temperature range.

Samples of critical area:

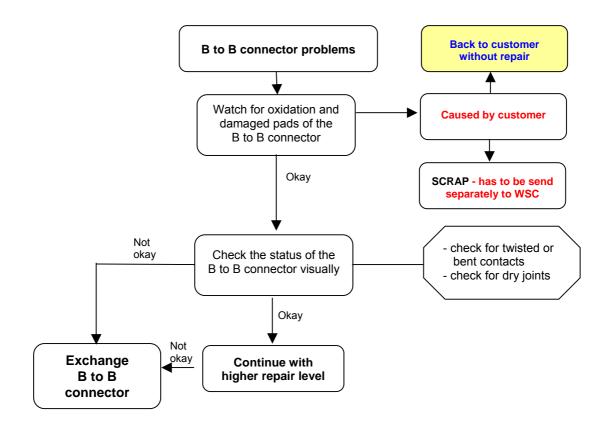






7 B to B connector (upper slider part) problems

Fault Symptoms	
Customer:	GRT:
Upper slider keyboard malfunction	Keyboard malfunction
Upper slider keypad illumination does not work	Current measured failed
Display problems	



Connector Board to Board

Use hot air blower to remove defective component. Avoid excessive heat! Watch surrounding components! Resolder new component afterwards.

E-commerce order number: L50334-Z97-C529

E-commerce order name: CONN BTB D1.5 18P BQ21.N1003.011

Soldering temperature: ~ 360°C TIP Temp.

IRIS Diagnose Code: 32100 Keys / Main / No Function

32200 Keys / Main / Reduced Functionality

36000 Keys / Illumination

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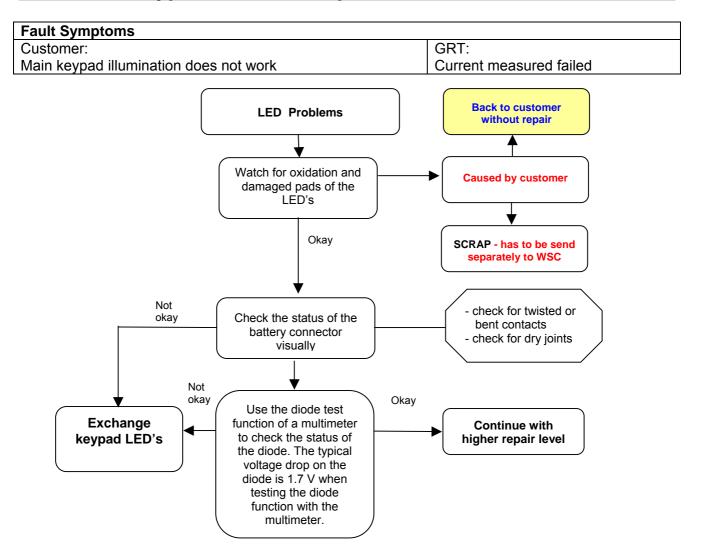
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8 Main keypad illumination problems



LED WHITE TOP

Use soldering iron to remove defective component. Avoid excessive heat! Watch surrounding components! Resolder new component afterwards.

Attention: Remove Metal Dome Sheet before!!!

E-commerce order number: L50840-L2133-D670

E-commerce order name: DISDIODE LED BL-HB536G BQ83.00536.071

Soldering temperature: ~ 360°C TIP Temp.

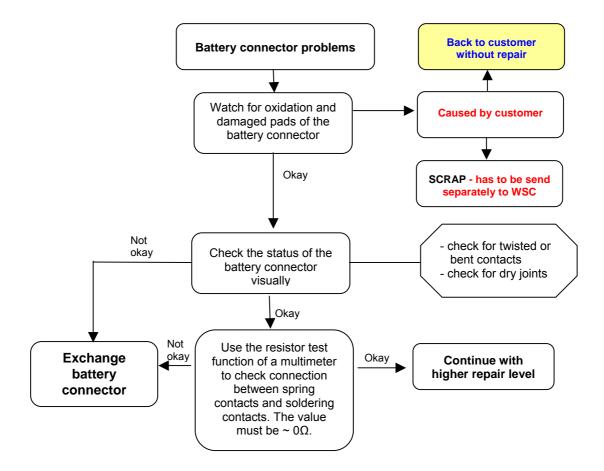
IRIS Diagnose Code: 36000 Keys / Illumination

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9 Connector Battery

Fault Symptoms		
Customer:	GRT:	
Mobile does not switch on	No connection to GRT	



Connector BATTERY

Use hot air blower to remove defective component. Avoid excessive heat! Watch surrounding components! Resolder new component afterwards.

E-commerce order number: L50334-Z97-C524

E-commerce order name: CON BATT3P CBE-4517-2904H BQ21.N0036.011

Soldering temperature: 240 - 255°C

IRIS Diagnose Code: 13000 Battery/Mechanical Damage

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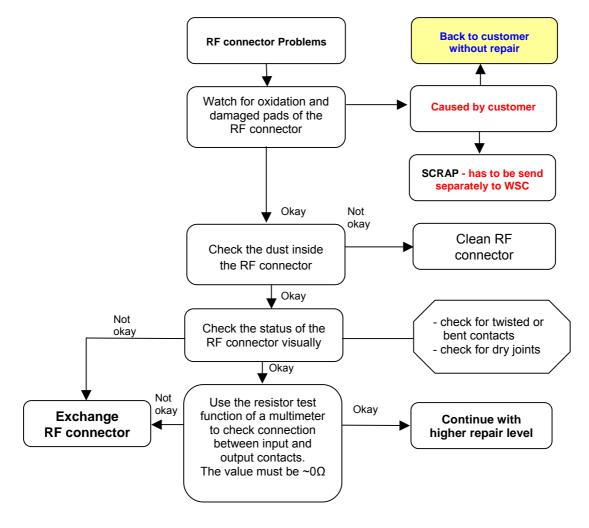
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10 Connector RF Internal Antenna

Fault Symptoms	
Customer:	GRT:
Network search	Failure by TX/RX measurements
No location update possible	No location update possible



Connector RF

Use hot air blower to remove defective component. Avoid excessive heat! Watch surrounding components! Resolder new component afterwards.

E-commerce order number: L50145-K280-Y415

E-commerce name: SWITCH ANT MS-147 HIROSE BQ69.50017.001

Soldering temperature: 240 - 255°C

IRIS Diagnose Code:

81100 Radio / No Contact / Int. Antenna 81200 Radio / No Contact / Ext. Antenna

82100 Radio / Low Receiving Signal / Int. Antenna 82200 Radio / Low Receiving Signal / Ext. Antenna

83100 Radio / Dropped Calls / Int. Antenna 83200 Radio / Dropped Calls / Ext. Antenna 84100 Radios / Call Setup / Int. Antenna 84200 Radio / Call Setup / Ext. Antenna

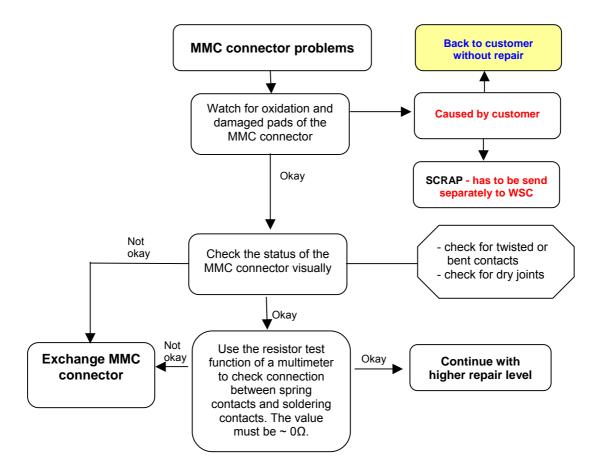
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11 Connector Mini SD

Fault Symptoms	
Customer:	GRT:
MMC malfunction	Tbd.



Connector MMC

Use soldering iron to remove defective component. Avoid excessive heat! Watch surrounding components! Resolder new component afterwards.

E-commerce order number: L50334-Z97-C528

E-commerce order name: CONN MINI SD 9P 500525 BQ21.N0058.011

Soldering temperature: ~ 360°C TIP Temp.

IRIS Diagnose Code: 4E000 Interfaces/ Memory Card Reader

Attention: Avoid excessive heat in order not to damage the plastic material of the connector (see problem SLIM-Lumberg connector)

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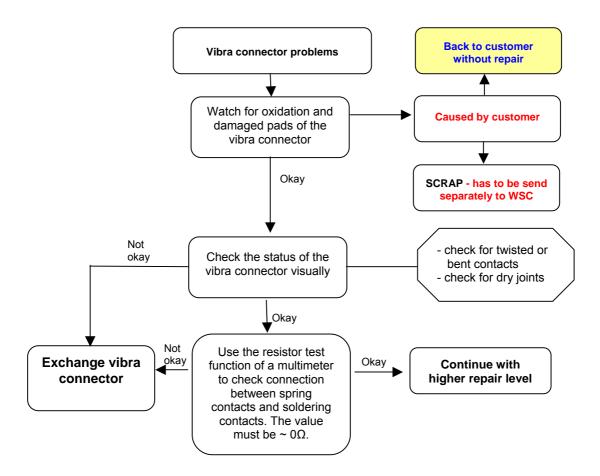
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12 Connector Vibra

Fault Symptoms		
Customer:	GRT:	
VIBRA does not work	Supported in April	



VIBRA Connector

Use hot air blower to remove defective component. Avoid excessive heat! Watch surrounding components! Resolder new component afterwards.

E-commerce order number: L50334-Z97-C525

E-commerce order name: CONN SPRING SBS23-2K30F00 BQ21.N0045.011

Soldering temperature: 240 - 255°C.

IRIS Diagnose Code: 75100: Acoustics / Vibra /No Function

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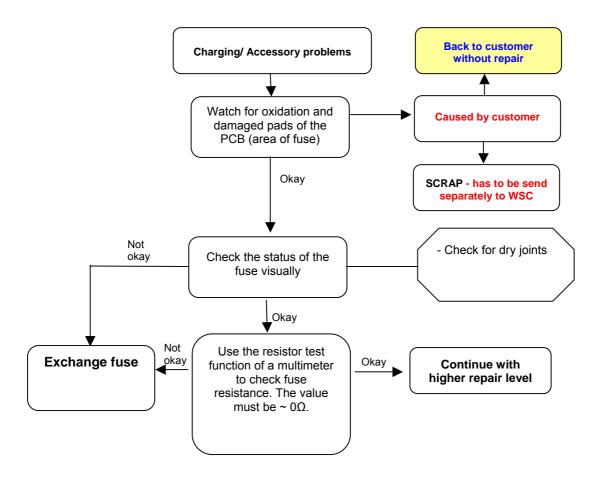
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13 Fuse

Fault Symptoms	
Customer:	GRT:
Battery charging does not work	Supported in April



<u>Fuse</u>

Use hot air blower to remove defective component. Avoid excessive heat! Watch surrounding components! Resolder new component afterwards.

E-commerce order number: L50145-A820-Y23

E-commerce order name: FUSE 1A 24V F0603 1608FF BQ69.41004.001

Soldering temperature: 240 - 255°C

IRIS Diagnose Code: 11000 Battery / No charging / deep discharge

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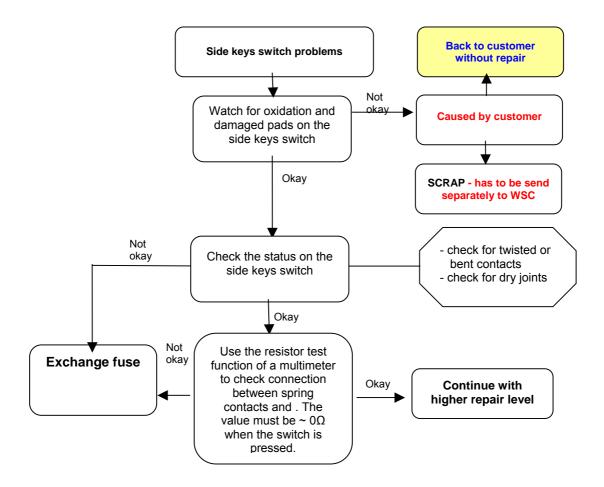
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14 Connector Sidekeys

Fault Symptoms		
Customer:	GRT:	
Pressing feeling is bad	Supported in April	
No function while pressing	Supported in April	



Side key switch

Use hot air blower to remove defective component. Avoid excessive heat! Watch surrounding components! Resolder new component afterwards.

E-commerce order number: L50315-Z77-C261

E-commerce order name: SWI VOLUME KEY 5P BQ21.P0004.005

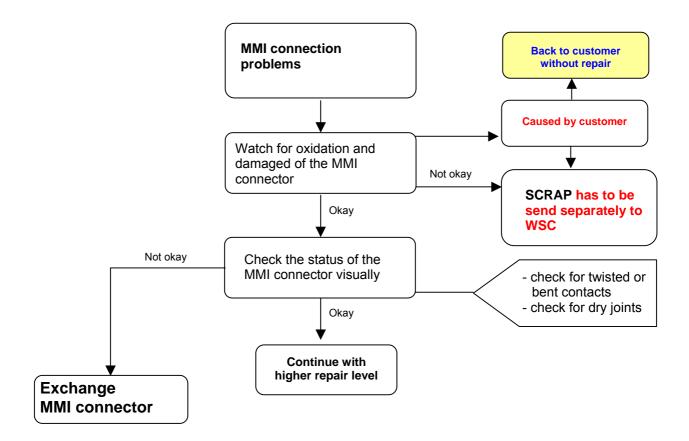
Soldering temperature: 240 - 255°C IRIS Diagnose Code: 34100 Keys / Side

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15 Connector MMI

Fault Symptoms	
Customer:	GRT:
Keyboard malfunction	Keyboard malfunction



Connector MMI

Use soldering iron to remove defective component. Avoid excessive heat! Watch surrounding components! Resolder new component afterwards.

E-commerce order number: L50315-Z77-C261

E-commerce order name: SWI VOLUME KEY 5P BQ21.P0004.005

Soldering temperature: 240 - 255°C
IRIS Diagnose Code: 34100 Keys / Side

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